

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S18	1844	(electroplat\$3 electrodeposit\$3) and (pressure pressurized vacuum) same (back backside non adj plating nonplating) with (wafer substrate workpiece microelectronics)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 14:00
S19	928	(electroplat\$3 electrodeposit\$3) and (pressure pressurized vacuum) with (back backside non adj plating nonplating) with (wafer substrate workpiece microelectronics)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 14:01
S20	225	S19 and ("204" "205").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 16:06
S26	2	"5227041".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 16:09
S25	91	"5,227,041"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 16:09
S23	110	S22 and ("204" "205").clas. and contact with (back backside) with (wafer substrate WSID)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 16:09
S22	928	(electroplat\$3 electrodeposit\$3) and (pressure pressurized vacuum) with (back backside non adj plating nonplating) with (wafer substrate workpiece microelectronics)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 17:32
S29	45	S28 not S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 17:34

## EAST Search History

S28	93	(electroplat\$3 electrodeposit\$3) and (back backside non adj plating nonplating) with (wafer substrate workpiece microelectronics wsid) with contact adj (ring pin fingers)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 17:34
S30	70	jung-Chih near2 tsao Kei-Wei near2 Chen Chi-Wen near2 Liu Shi-Chi near2 Lin Ray near2 Chuang	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 18:15
S31	1	S30 and contact adj ring with (backside back adj side non adj plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 18:16
S34	26	S30 and electroplating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 18:17
S33	1	S30 and contact adj (ring finger pin) same (backside back adj side non adj plating back)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 18:17
S32	1	S30 and contact adj (ring finger pin) with (backside back adj side non adj plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 18:17